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LPKF introduces laser direct structuring for 3D circuits

Garbsen, April 2011 - LPKF Laser & Electronics introduces the new Fusion3D 1100, designed to create three dimensional circuits and laser-structuring of molded interconnect devices (MID) for small volume production. The system is easy to install and can be incorporated into any work environment due to its compact size.

The Fusion3D 1100 has no restrictions in terms of 3D freedom and utilizes laser direct structuring technology (LDS) and MID to combine both mechanical structures and electronic circuits into a single 3D part. MID consists of circuit traces embedded into molded thermoplastics which creates an electrical pathway. The 3D circuits are structured by using LDS-grade resin which is laser activated by a scanner based laser system. The circuit pattern is written directly on the molded piece and conductive paths are plated using electroless plating technology, adhering only to where the plastic has been activated by the laser beam.

"With its compact size, substantially lower price, and advanced technology, the new LPKF laser structuring system creates an opportunity for further growth of affordable LDS technology," explains Dr. Ingo Bretthauer, CEO of LPKF Laser & Electronics. LPKF is expecting to start delivery of the Fusion3D 1100 systems to North American customers in July 2011.

About LPKF

LPKF Laser & Electronics is the world leading manufacturer of both mechanical and laser systems for demanding tasks in printed circuit board technology and microelectronics. LPKF's worldwide headquarters is located in Garbsen, Germany outside of Hannover and maintains North American headquarters in Portland, OR. More information is available at LPKF's website: www.lpkfusa.com



Image found at: www.lpkfusa.com/images/LPKF_342_Fusion_1000.jpg

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